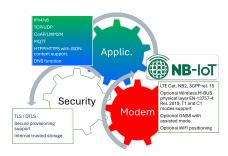


STSW-ST87M01 firmware





Product status link

STSW-ST87M01

Features

- Application interface:
 - 3GPP TS 27.005, 3GPP TS 27.007 and ITU-T recommendation V.25ter commands set
 - ST proprietary AT commands set
- Connectivity:
 - LTE Cat. NB2, 3GPP rel. 15
 - Optional Wireless M-BUS physical layer EN-13757-4 Rel. 2019, T1 and C1 modes support
- Application protocols:
 - IPv4/v6
 - TCP/UDP
 - CoAP/LwM2M
 - MQTT
 - HTTP/HTTPS
- DNS function
- Localization functions:
 - Optional GNSS with assisted mode
 - 2 output formats supported: proprietary AT command and NMEA string format
- Security:
 - TLS/DTLS
 - Secure provisioning support (internal trusted storage)
- Extra functions:
 - Energy consumption estimation
 - Battery voltage monitoring
 - Module I/O management
 - Network status indication

Description

This package contains the firmware bundle for the STSW-ST87M01 module family. The bundle is composed of three or four image files depending on the specific module part number. The module supports the following three types of bundles:

Type 1 = NB-IoT FW + Secure FW + Application FW

Type 2 = NB-IoT FW + Secure FW + Application FW + GNSS Wi-Fi FW

Type 3 = NB-IoT FW + Secure FW + Application FW + WMBUS FW.



Revision history

Table 1. Document revision history

Date	Version	Changes
18-Mar-2025	1	Initial release.

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